

**In the Drawings:**

Proposed changes to Figs. 2 and 5-8 are shown in red in the attached copies of Figs. 2 and 5-8. The marked up copies of Figs. 2 and 5-8 are on pages 10 and 11 of this Office Action Response. These changes add appropriate cross-hatching to the drawings for the flexible tape and the encapsulation material as required by the Examiner. It is requested that actual changes to the drawings be held in abeyance until allowance of the claims has been determined.

**In the Specification:**

Please rewrite the two paragraphs from page 10, line 1 to page 11, line 1 as follows.

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Refer now to Figs. 7 and 8 for a description of some particular examples of molded circuit elements 12. Fig. 7 shows a first example of a molded circuit element 12 having a circuit die 30 attached to the flexible tape 10. The flexible tape 10 is a flexible material such as polyimide or the like. Copper pads 34 are formed on the opposite side of the flexible tape from the circuit die 30. Wire bonds using a material such as gold wire 32 are bonded to the circuit die 30 and to the copper pads 34 through via holes 40 in the flexible tape 10. Solder balls 36 are attached to the copper pads 34 through a solder mask 38 formed of a material not wettable by the solder. The circuit die